



SECURING & REINFORCING

Hi-Rel Electronics Supply Chains

Micross extensive experience with technology reaching end-of-life (EOL), have developed an in-depth understanding of how to manage semiconductor obsolescence and mitigate the risks associated.



TRADITIONAL PROGRAM/PRODUCT LIFECYCLE



Micross DMS/Obsolescence Sustainment Solutions

PROACTIVE SOLUTIONS

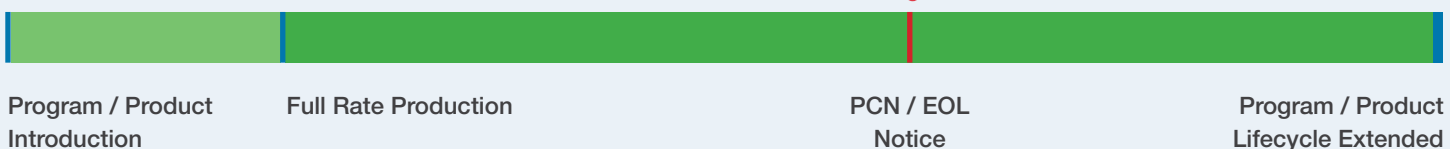
- EOL Die Sustainment Program (EDSP)
- Access to Broadest Supply of Die & Wafer
- BOM Monitoring & Reporting
- Long Term Die, Wafer, & Component Storage
- Supplier Managed Inventory



REACTIVE SOLUTIONS

- Product Reconditioning (Original Qualified Product)
- Product Recreation (FFF Equivalent)
- Equivalent Die Characterization & Sourcing
- Up-Screening to Industrial, Military, or Space-Grade
- Component Harvesting
- Counterfeit Mitigation

MICROSS COMPLETE LIFECYCLE SECURITY



Program & Product Sustainment Solutions

ORIGINAL QUALIFIED PRODUCT

EOL Die Sustainment Program (EDSP)

EDSP supports customers in challenging situations where a product has or will become end-of-life.

EDSP maintains the authorized chain of custody, providing exact drop in replacement die, or fully packaged solutions, utilizing the original qualified die, thereby eliminating the need for costly re-qualification or design changes.

Access to Broadest Supply of Global Die

Micross has the largest authorized line card for bare die & wafers in the industry.

Trusted Partner for Counterfeit Mitigation

When hard to find obsolete original parts cannot be sourced, Micross enables customers to sustain their programs using non-franchised parts. These parts are tested to the requirements of the original part and or to the customer's requirements.

Component Reconditioning

When Military or Space-Grade products are not available, Micross will recondition COTS product to OEM specifications.

Component Harvesting

Components are harvested using fully automated process, eliminating the risk of bent or damaged leads, and the potential of thermal damage to the harvest components and circuit board.

FORM-FIT-FUNCTION EQUIVALENT

Equivalent Die Characterization & Sourcing

Micross has the expertise to characterize and reverse engineer devices, along with the broadest access to source functionally equivalent die.

Product Recreation

When the original die is not available, Micross can product a form-fit-function recreation. Interposers and redistribution layers (RDLs) enable functionally equivalent die to be packaged into a direct drop-in-replacement of the original device.

PEMS/COTS Upscreening

When original parts are not available, Micross has a broad range of capabilities from standard upscreening to complete turnkey PEMS/COTS upscreening and qualification.

PROGRAM SUSTAINMENT MANAGEMENT

BOM Monitoring & Reporting

Micross's BOM monitoring services utilize the most advanced technology & resources to help ensure uninterrupted product supply.

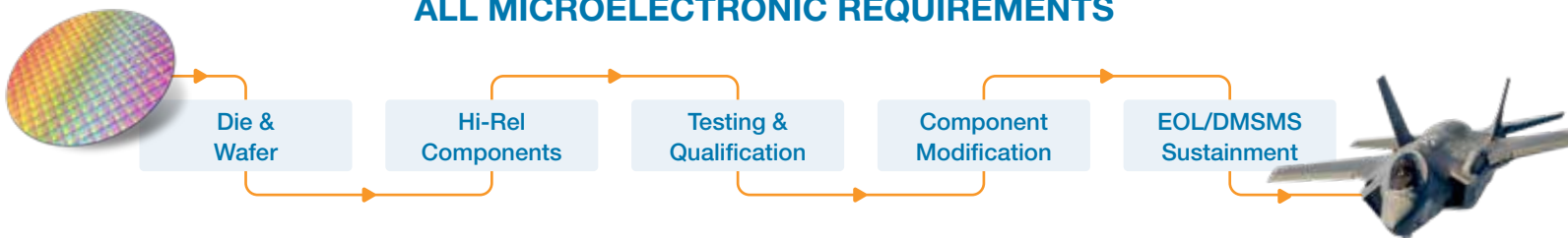
Long Term Die Storage

Micross provides semiconductor die/wafer procurement & storage as well as large-capacity bare die banks, which can hold stock from a single diffusion run to assure homogeneity. Products are stored in special smoke and water-resistant containers in a dry nitrogen environment that prevents contamination.

Supplier Managed Inventory (SMI)

Micross' SMI solutions enable OEMs to outsource their inventory management and ensure program/product sustainment is maintained, utilizing all the resources and services available through Micross DMS / Sustainment solutions.

UNIQUELY ABLE TO SUPPORT ALL MICROELECTRONIC REQUIREMENTS



About Micross

Micross is the most complete provider of advanced microelectronic services and component, die and wafer solutions. With the broadest authorized access to die & wafer suppliers, an extensive portfolio of hi-rel power, RF, optoelectronics, memory, data bus, logic, and SMD/5962 qualified products, and the most comprehensive advanced packaging, assembly, modification, upscreening, and test capabilities, Micross is uniquely positioned to provide unparalleled high-reliability solutions, from bare die, to fully packaged devices including hermetic ICs/MCMs, PEMS, ASICs, FPGAs, and PCBs, to complete program life-cycle sustainment. For more than 45 years, Micross has been a trusted source for the aerospace, defense, space, medical, energy, communications, and industrial markets.



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